

## IN THE CLAIMS

*A listing of the claims presented in this patent application appears below. This listing replaces all prior versions and listing of claims in this patent application.*

### *Claims 1-10 (Cancelled)*

[11] (New)           A semiconductor laser device comprising:  
a semiconductor laser element;  
a frame having a front face on which the semiconductor laser element is placed; and  
a resin molded portion that covers the front and back faces of the frame,  
wherein, on a front face side of the frame,  
the semiconductor laser element is enclosed with the resin molded portion, and  
the resin molded portion has an open front serving as a laser beam emission window,  
wherein, on a back face side of the frame, there is provided an exposed portion  
enclosed with the resin molded portion having an open front, the exposed portion  
where the frame is exposed to an outside, and  
wherein the frame includes  
an element placement portion on which the semiconductor laser element is placed,  
a lead portion that is integrally formed with the element placement portion, the  
lead portion that serves as a current path with a wire connected thereto, and  
a tapered portion provided between the element placement portion and the lead  
portion, the tapered portion whose width is gradually reduced from the element  
placement portion toward the lead portion.

[12] (New)           The semiconductor laser device of claim 1, further comprising:  
a gate mark of an injection gate through which molding resin is injected, the gate mark  
provided above the tapered portion.

[13] (New)           A semiconductor laser device comprising:

a semiconductor laser element;  
a frame having a front face on which the semiconductor laser element is placed; and  
a resin molded portion that covers the front and back faces of the frame,  
wherein, on a front face side of the frame,  
the semiconductor laser element is enclosed with the resin molded portion, and  
the resin molded portion has an open front serving as a laser beam emission window,  
wherein, on a back face side of the frame, there is provided an exposed portion  
enclosed with the resin molded portion having an open front, the exposed portion  
where the frame is exposed to an outside, and  
wherein the frame includes  
an element placement portion on which the semiconductor laser element is placed,  
and  
a lead portion having a width of 0.4 mm or more that is integrally formed with the  
element placement portion, the lead portion that serves as a current path with a wire  
connected thereto.

[14] (New) A semiconductor laser device comprising:  
a semiconductor laser element;  
a frame having a front face on which the semiconductor laser element is placed; and  
a resin molded portion that covers the front and back faces of the frame,  
wherein, on a front face side of the frame,  
the semiconductor laser element is enclosed with the resin molded portion, and  
the resin molded portion has an open front serving as a laser beam emission window,  
wherein, on a back face side of the frame, there is provided an exposed portion  
enclosed with the resin molded portion having an open front, the exposed portion  
where the frame is exposed to an outside,  
wherein the frame includes  
an element placement portion on which the semiconductor laser element is placed,  
a lead portion that is formed integrally with the element placement portion, the  
lead portion that serves as a current path with a wire connected thereto, and

subframes that are arranged in parallel on both sides of the lead portion and are integrated with the lead portion by the resin molded portion, the subframes that serve as current paths with wires connected thereto, and wherein a width of the lead portion is made greater than a width of each of the subframes.

- [15] (New)           A method of manufacturing a semiconductor laser device comprising: a semiconductor laser element; a frame having a front face on which the semiconductor laser element is placed; and a resin molded portion that covers the front and back faces of the frame,
- wherein, on a front face side of the frame,
- the semiconductor laser element is enclosed with the resin molded portion, and
- the resin molded portion has an open front serving as a laser beam emission window,
- wherein, on a back face side of the frame, there is provided an exposed portion
- enclosed with the resin molded portion having an open front, the exposed portion
- where the frame is exposed to an outside,
- wherein the frame includes
- an element placement portion on which the semiconductor laser element is placed,
- a lead portion that is integrally formed with the element placement portion, the
- lead portion that serves as a current path with a wire connected thereto, and
- a tapered portion provided between the element placement portion and the lead
- portion, the tapered portion whose width is gradually reduced from the element
- placement portion toward the lead portion, and
- wherein the resin molded portion is formed by injecting molding resin from above the
- tapered portion.

- [16] (New)           A method of manufacturing a semiconductor laser device comprising: a semiconductor laser element; a frame having a front face on which the semiconductor laser element is placed; and a resin molded portion that covers the front and back faces of the frame,
- wherein, on a front face side of the frame,

the semiconductor laser element is enclosed with the resin molded portion, and the resin molded portion has an open front serving as a laser beam emission window, wherein, on a back face side of the frame, there is provided an exposed portion enclosed with the resin molded portion having an open front, the exposed portion where the frame is exposed to an outside, wherein the frame includes

- an element placement portion on which the semiconductor laser element is placed,
- and
- a lead portion having a width of 0.4 mm or more that is integrally formed with the element placement portion, the lead portion that serves as a current path with a wire connected thereto, and

wherein the resin molded portion is formed by injecting molding resin from above the leading portion.